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Understanding PCB Design & Material Warpage Challenges – Learn More at SMTAI

ATLANTA, GA — September 23, 2016 — Akrometrix, LLC, the leading provider of thermal warpage and strain metrology equipment to both the front- and back-end semiconductor and electronics industries, today announced that Ryan Curry, Technical Account Manager, will co-present a paper with Don Adams, Manufacturing Engineering Manager at Bose Corporation, during SMTA International. The presentation, "Understanding PCB Design and Material Warpage Challenges Which Occur during B2B/Module-Carrier Attachment," is scheduled to take place during session APT7, "Package and PCB Interactions," on Wednesday, September 28th at 4 p.m.

PCB warpage has been identified as one of several key contributors to unacceptable yield rates during reflow assembly of a PCB module to a PCB carrier board. The module has a land grid array pattern and is placed directly on solder paste on the carrier board. This results in low-profile solder joints that are sensitive to the co-planarity of both the module and the carrier boards. The typical failure mode occurs when one or more solder joint opens are caused by a lifted corner of the module during/after reflow.

This paper and presentation will present graphical and statistical details of at-room-temperature metrology on a large sample of modules with differing design variables. Shadow Moiré technique will be used to provide accurate warpage profiles of the 6-up module arrays before and after top- and bottom-side assembly, and again before and after attachment to the carrier board. A large volume of samples will be tested in order to gain statistical relevance of the data and correlate any yield problems to initial warpage. The objective is to isolate the key design parameter(s) that contribute most to attachment problems while also observing and reporting on the at-temperature warpage behavior of the substrates during reflow.

Curry is the Technical Account Manager at Akrometrix, having shifted to this role after almost 11 years of experience as a Test and Applications Engineer. He is a subject matter expert in at temperature warpage and strain measurement techniques. Curry has experience with frequent use of Akrometrix measurement tools for contract testing services and demonstration work, along with domestic and international customer support, technical sales, outgoing system quality assurance, software and NPI development work, and Akrometrix system installation and user training. He has a degree in Mechanical Engineering from the Georgia Institute of Technology.

For more information about Akrometrix, please contact sales.akrometrix.com or visit www.akrometrix.com.

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About Akrometrix LLC

Akrometrix is the leader in thermal warpage and strain metrology for the front-end/back-end wafer, back-end packaging/assembly, panel and the PCB/component markets. The company provides both capital equipment and test services to measure warpage and strain in temperatures from -50°C to 300°C on virtually any substrate up to 600mm x 600mm, regardless of shape. Located in Atlanta, Georgia, Akrometrix has been serving customers worldwide for more than 20 years based on technology developed at Georgia Tech. For more information, contact Akrometrix at Sales@Akrometrix.com or visit www.Akrometrix.com.

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